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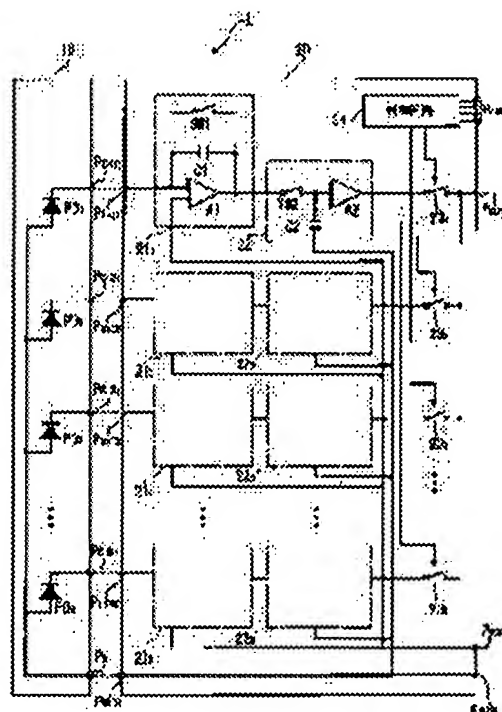
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(54) SOLID-STATE IMAGE PICKUP DEVICE

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a solid-state image pickup device in which the number of photoreceptor elements can be increased easily and which can be manufactured highly efficiently at a low cost.

SOLUTION: This solid-stage image pickup device 1 is provided with first and second substrates 10 and 20. On the first substrate 10, photodiodes PD1-PDN are two-dimensionally arranged and pads PC(1)-PC(N) and PA for bump connections are formed. On the second substrate 20, integration circuits 211-21N, hold circuits 221-22N, switch elements 231-23N, and a control circuit 24 are formed, and pads Pin(1)-Pin(N) and PGND1 for bump connections are formed. The pad PC(n) on the first substrate 10 is bump-connected to the pad Pin(n) on the second substrate 20. In addition, the pad PA on the first substrate 10 is bump-connected to the pad PGND1 on the second substrate 20.



LEGAL STATUS

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